



100% Material Declaration Data Sheet FFG323

PK235 (v1.0) December 12, 2007

Material Declaration Data Sheet

Average Weight: 2.8477 g

| Component | Substance Description | CAS# or Description | % of Component | Use in Product | Component Weight/ Substance Weight (in grams) | Component % of Total |
|-------------------------------|----------------------------|---------------------|----------------|----------------|---|-------------------------|
| Silicon Die | | | | | 0.000010 | 0.000% |
| | Silicon | 7440-21-3 | 100.00 | | 0.000010 | |
| Solder Bump | | | | | 0.016860 | 0.592% |
| | Tin | 7440-31-5 | 63.00 | | 0.010622 | |
| | Lead | 7439-92-1 | 37.00 | | 0.006238 | |
| Underfill | | | | | 0.056000 | 1.966% |
| | Silica | 60676-86-0 | 70.00 | | 0.039200 | |
| | Epoxy Resin A | 9003-36-5 | 20.00 | | 0.011200 | |
| | Epoxy Resin B | 25068-38-6 | 3.00 | | 0.001680 | |
| | Hardener | 19900-65-3 | 7.00 | | 0.003920 | |
| Heat Spreader | | | | | 1.100000 | 38.627% |
| | Copper | 7440-50-8 | 99.60 | | 1.095600 | |
| | Nickel | 7440-02-0 | 0.40 | | 0.004400 | |
| Heat Spreader Adhesive | | | | | 0.031000 | 1.089% |
| | Organopolysiloxane mixture | N/A | 100.00 | | 0.031000 | |
| Substrate | | | | | 1.343877 | 47.191% |
| | Copper | 7440-50-8 | 47.61 | Metal Layer | 0.639826 | |
| | Nickel | 7440-02-0 | 0.51 | Metal Layer | 0.006854 | |
| | Gold | 7440-57-5 | 0.11 | Metal Layer | 0.001478 | |
| | Glass fiber | N/A | 10.35 | | 0.139093 | |
| | Halogen fire retardant | N/A | 5.25 | | 0.070500 | |
| | BT (core) | N/A | 27.54 | | 0.370148 | |
| | Solder Mask | N/A | 8.63 | | 0.115978 | |
| Solder Balls | | | | | 0.300000 | 10.535% |
| | Tin | 7440-31-5 | 95.50 | | 0.286500 | |
| | Silver | 7440-22-4 | 4.00 | | 0.012000 | |
| | Copper | 7440-50-8 | 0.50 | | 0.001500 | |

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Revision History

The following table shows the revision history for this document.

| Date | Revision | Revision |
|----------|----------|------------------|
| 12/12/07 | 1.0 | Initial release. |